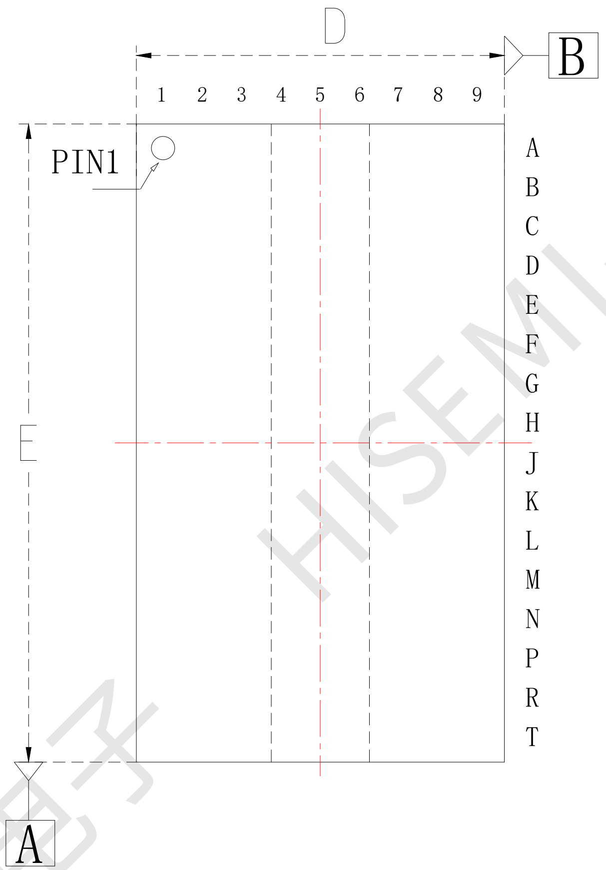
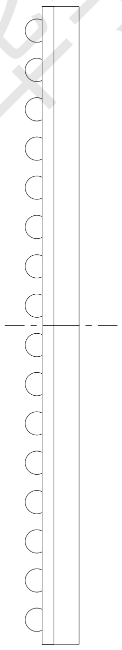
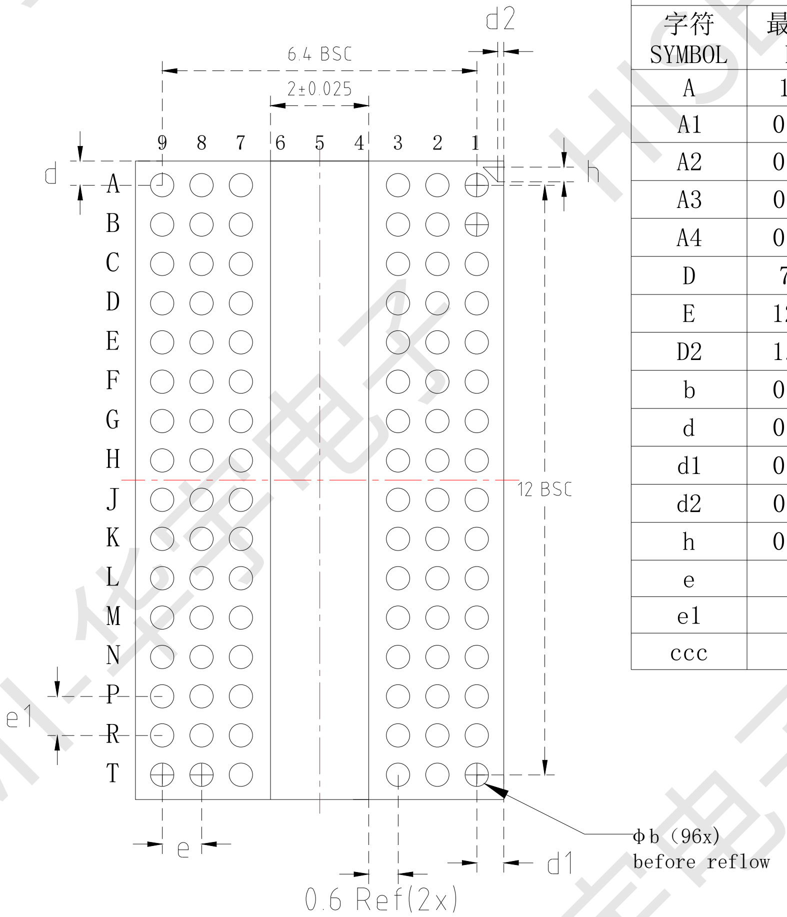
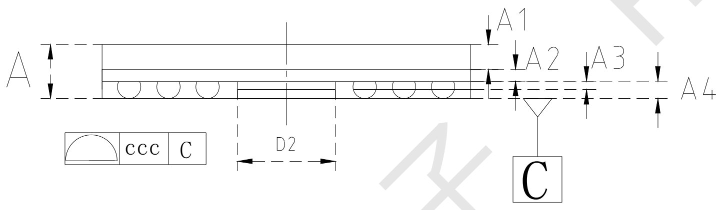
RoHS







机械尺寸/mm			
字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	1.00	1.10	1.20
A1	0.460	0.510	0.560
A2	0.220	0.240	0.260
A3	0.135	0.155	0.175
A4	0.250	0.350	0.400
D	7.40	7.50	7.60
E	12.00	13.00	14.00
D2	1.975	2.00	2.025
b	0.400	0.450	0.500
d	0.450	0.500	0.550
d1	0.500	0.550	0.600
d2	0.075	0.125	0.175
h	0.250	0.300	0.350
e	0.800 BSC		
e1	0.800 BSC		
ccc	0.100 max		



TECHNOLOGY SPECIFICATION[技术要求]
1.PRIMARY DATUM C AND SEATING PLANE ARE THE SOLDER BALLS:
[主要基准C和底面是锡球;]
2.SDIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLELTO PRIMARY DATUM C;[尺寸b是测量最大锡球直径，平行于主要基准C;]
3.SPECIAL CHARACTERISTICS C CLASS:bbb, ddd:[特殊特性C类:ccc, ddd;]
4.THE PATTERN OF PIN 1 FIDUCIAL IS FOR REFERENCE ONLY;
[PIN 1标识仅供参考;]
5.BAN TO USE THE LEVEL 1 ENVIRONMENT-RELATED SUBSTANCES:
[禁止使用一级环境管理物质;]

池州华宇电子科技股份有限公司
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

HY-POD-BGA0155

PACKAGE OUTLINE DIMENSIONS
WBGA96B（7.5X13X1.1-P0.8）

页数 page	单位 unit	比例 scale	视图 view
1	mm	1:1	⌖ ⏢

制图：Draw　NINGLIN 2026.2.4
制图核查：Drawing review
审核：Checker
核准：Approved